



# PMEG3030EP

30 V, 3 A low VF Schottky barrier rectifier

1 April 2023

Product data sheet

## 1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD128 small and flat lead Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Average forward current:  $I_{F(AV)} \leq 3 \text{ A}$
- Reverse voltage:  $V_R \leq 30 \text{ V}$
- Low forward voltage
- High power capability due to clip-bond technology
- Small and flat lead SMD plastic package
- Capable for reflow and wave soldering

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications

## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5; f = 20 \text{ kHz}; \text{square wave}; T_{sp} \leq 140 \text{ }^\circ\text{C}$	-	-	3	A
$V_R$	reverse voltage	$T_j = 25 \text{ }^\circ\text{C}$	-	-	30	V
$V_F$	forward voltage	$I_F = 3 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	315	360	mV
$I_R$	reverse current	$V_R = 30 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	1.5	5	mA

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]		 CFP5 (SOD128)
2	A	anode		 sym001

[1] The marking bar indicates the cathode.

## 6. Ordering information

**Table 3. Ordering information**

<b>Type number</b>	<b>Package</b>		
	<b>Name</b>	<b>Description</b>	<b>Version</b>
PMEG3030EP	CFP5	plastic, surface mounted package; 2 terminals; 4 mm pitch; 3.8 mm x 2.6 mm x 1 mm body	<a href="#">SOD128</a>

## 7. Marking

**Table 4. Marking codes**

<b>Type number</b>	<b>Marking code</b>
PMEG3030EP	A5

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

<b>Symbol</b>	<b>Parameter</b>	<b>Conditions</b>		<b>Min</b>	<b>Max</b>	<b>Unit</b>
$V_R$	reverse voltage	$T_j = 25 \text{ }^\circ\text{C}$		-	30	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20 \text{ kHz}$ ; square wave; $T_{amb} \leq 85 \text{ }^\circ\text{C}$	[1]	-	3	A
		$\delta = 0.5$ ; $f = 20 \text{ kHz}$ ; square wave; $T_{sp} \leq 140 \text{ }^\circ\text{C}$		-	3	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8 \text{ ms}$ ; square wave; $T_{j(init)} = 25 \text{ }^\circ\text{C}$		-	50	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25 \text{ }^\circ\text{C}$	[2]	-	0.625	W
			[3]	-	1.05	W
			[4]	-	2.1	W
$T_j$	junction temperature			-	150	$^\circ\text{C}$
$T_{amb}$	ambient temperature			-55	150	$^\circ\text{C}$
$T_{stg}$	storage temperature			-65	150	$^\circ\text{C}$

[1] Device mounted on a ceramic PCB,  $\text{Al}_2\text{O}_3$ , standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode  $1 \text{ cm}^2$ .

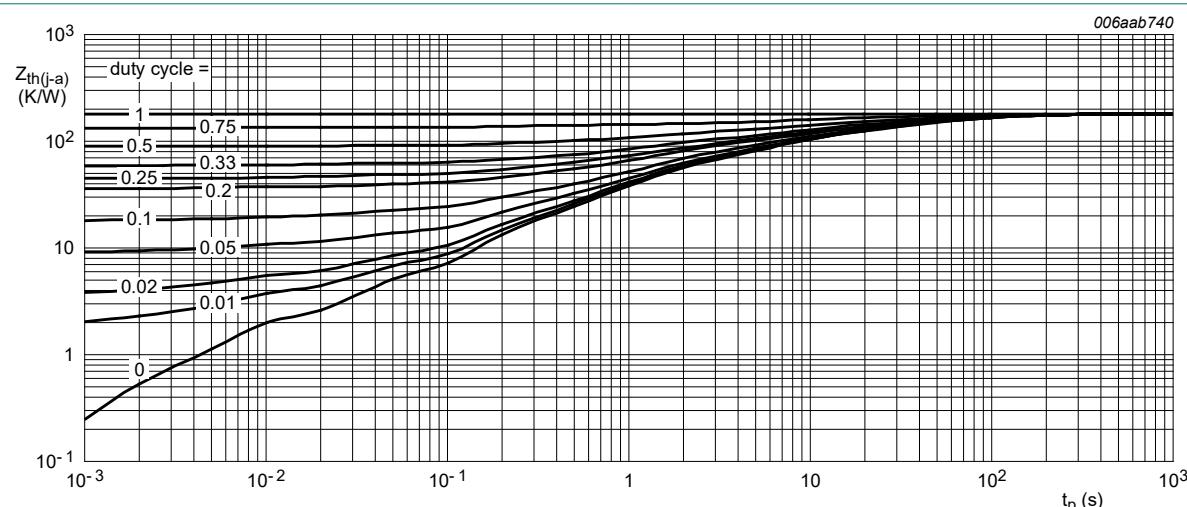
[4] Device mounted on a ceramic Printed-Circuit Board (PCB),  $\text{Al}_2\text{O}_3$ , standard footprint.

## 9. Thermal characteristics

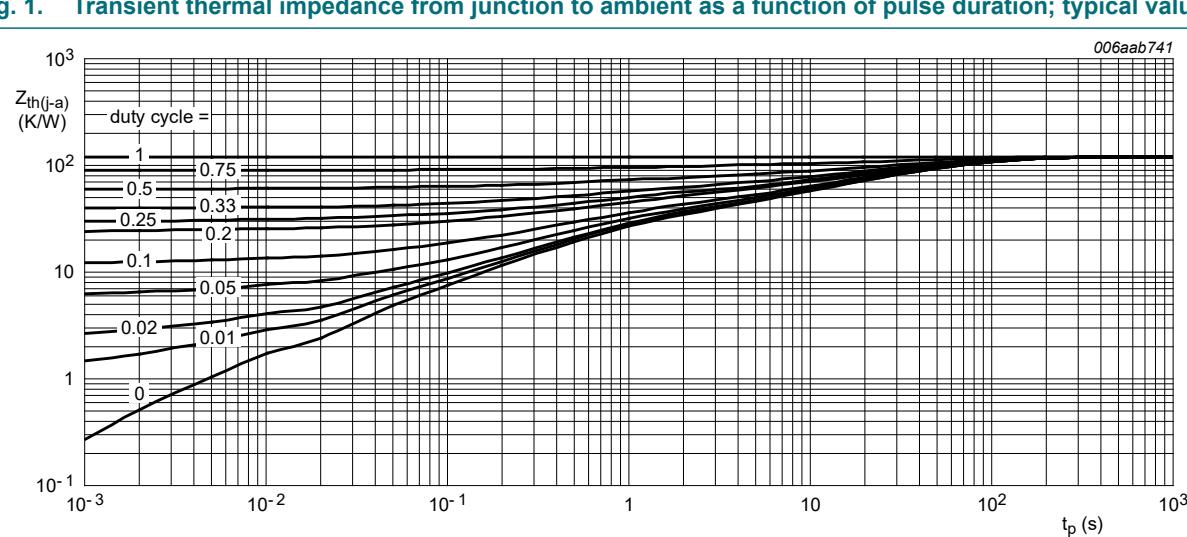
**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	200	K/W
			[1] [3]	-	-	120	K/W
			[1] [4]	-	-	60	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	12	K/W

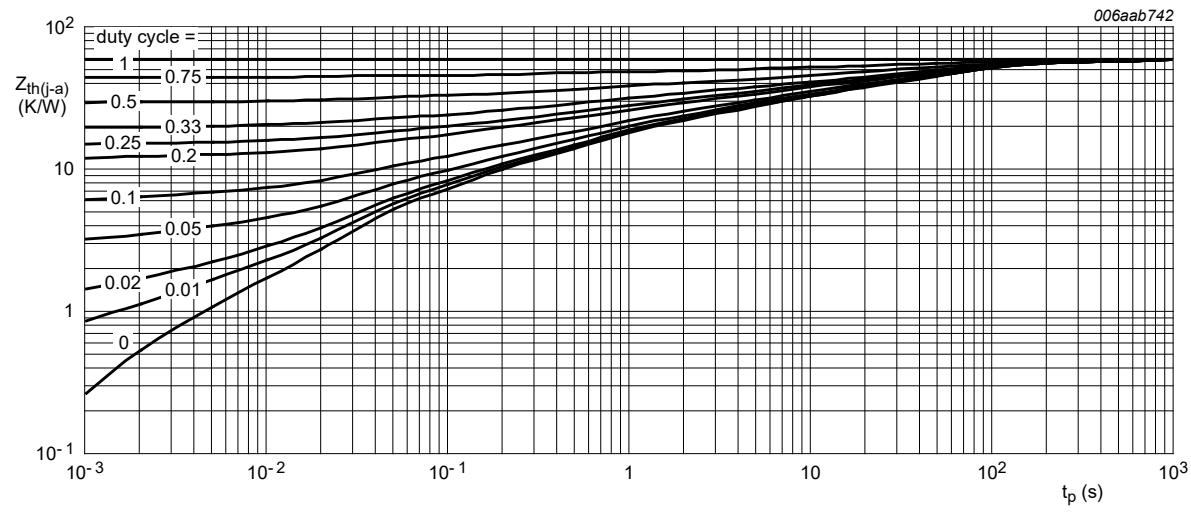
- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [5] Soldering point of cathode tab.



**Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



**Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



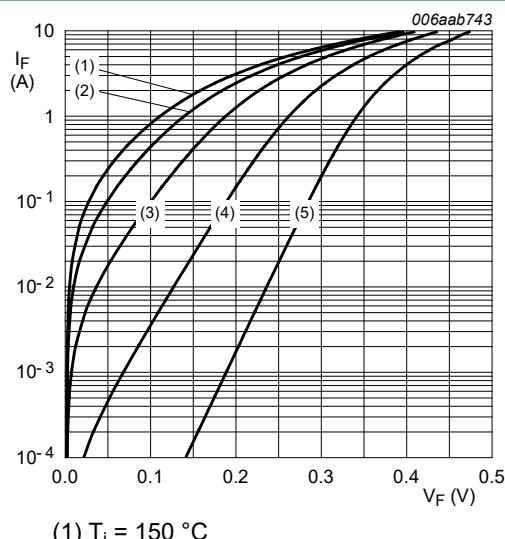
Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

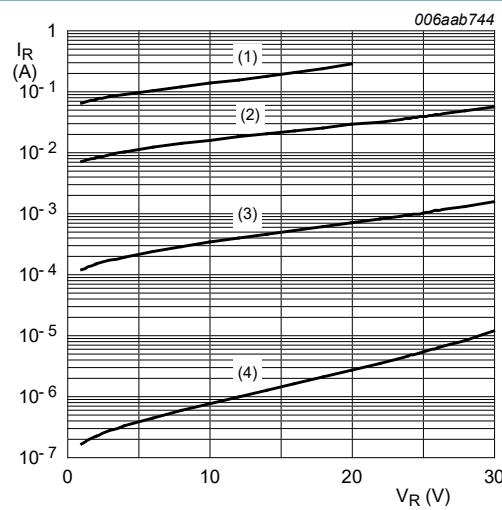
**Table 7. Characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage	$I_F = 0.5 \text{ A}; T_j = 25^\circ\text{C}$	-	235	270	mV
		$I_F = 1 \text{ A}; T_j = 25^\circ\text{C}$	-	260	290	mV
		$I_F = 3 \text{ A}; T_j = 25^\circ\text{C}$	-	315	360	mV
$I_R$	reverse current	$V_R = 5 \text{ V}; T_j = 25^\circ\text{C}$	-	190	-	$\mu\text{A}$
		$V_R = 30 \text{ V}; T_j = 25^\circ\text{C}$	-	1.5	5	mA
$C_d$	diode capacitance	$V_R = 1 \text{ V}; f = 1 \text{ MHz}; T_j = 25^\circ\text{C}$	-	470	-	pF
		$V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_j = 25^\circ\text{C}$	-	160	-	pF



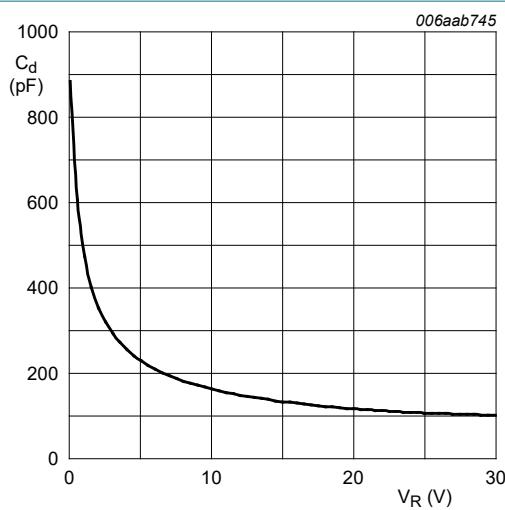
- (1)  $T_j = 150^\circ\text{C}$
- (2)  $T_j = 125^\circ\text{C}$
- (3)  $T_j = 85^\circ\text{C}$
- (4)  $T_j = 25^\circ\text{C}$
- (5)  $T_j = -40^\circ\text{C}$

**Fig. 4. Forward current as a function of forward voltage; typical values**



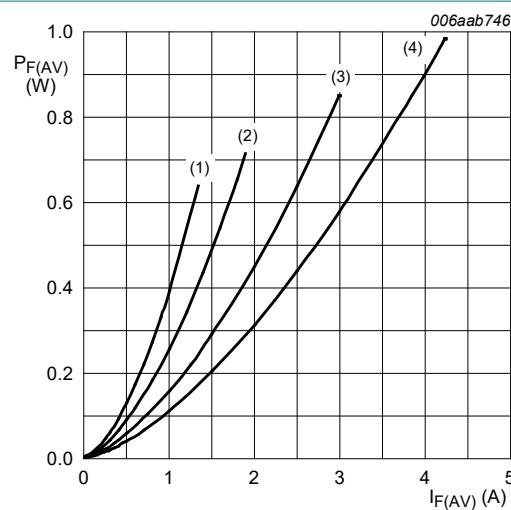
- (1)  $T_j = 125^\circ\text{C}$
- (2)  $T_j = 85^\circ\text{C}$
- (3)  $T_j = 25^\circ\text{C}$
- (4)  $T_j = -40^\circ\text{C}$

**Fig. 5. Reverse current as a function of reverse voltage; typical values**



$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^{\circ}\text{C}$

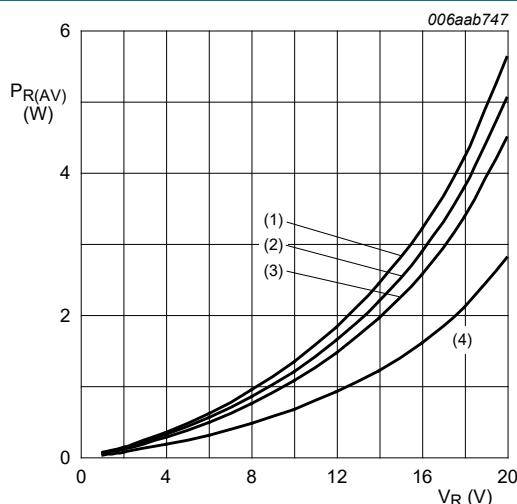
**Fig. 6. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 150 \text{ }^{\circ}\text{C}$

- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 1$

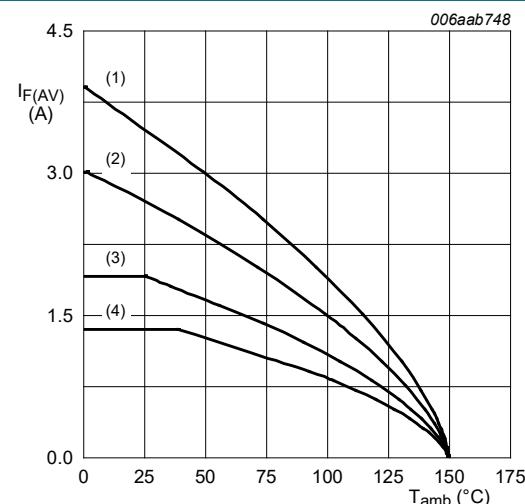
**Fig. 7. Average forward power dissipation as a function of average forward current; typical values**



$T_j = 125 \text{ }^{\circ}\text{C}$

- (1)  $\delta = 1$
- (2)  $\delta = 0.9$
- (3)  $\delta = 0.8$
- (4)  $\delta = 0.5$

**Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values**

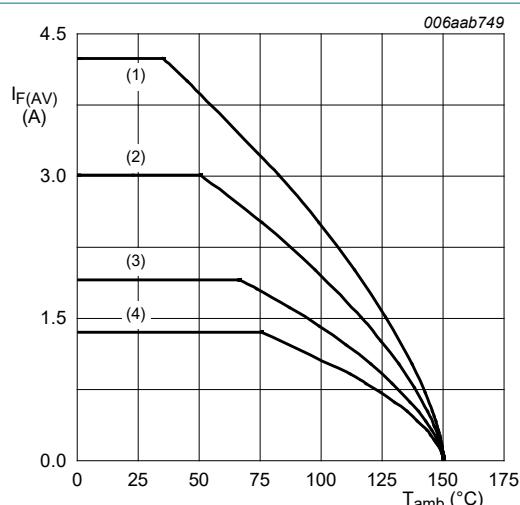


FR4 PCB, standard footprint

$T_j = 150 \text{ }^{\circ}\text{C}$

- (1)  $\delta = 1; \text{DC}$
- (2)  $\delta = 0.5; f = 20 \text{ kHz}$
- (3)  $\delta = 0.2; f = 20 \text{ kHz}$
- (4)  $\delta = 0.1; f = 20 \text{ kHz}$

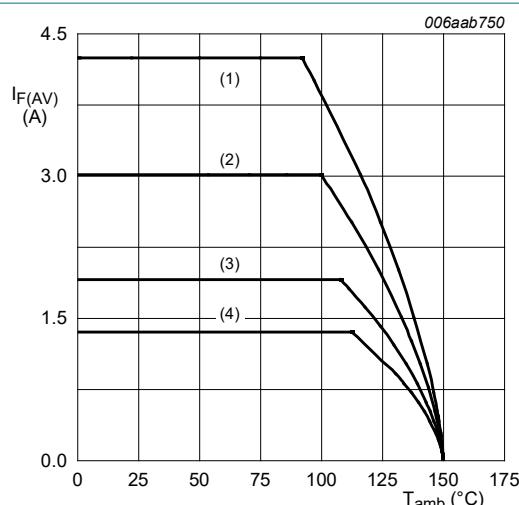
**Fig. 9. Average forward current as a function of ambient temperature; typical values**



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  
 $T_j = 150$   $^{\circ}$ C

- (1)  $\delta = 1$ ; DC
- (2)  $\delta = 0.5$ ; f = 20 kHz
- (3)  $\delta = 0.2$ ; f = 20 kHz
- (4)  $\delta = 0.1$ ; f = 20 kHz

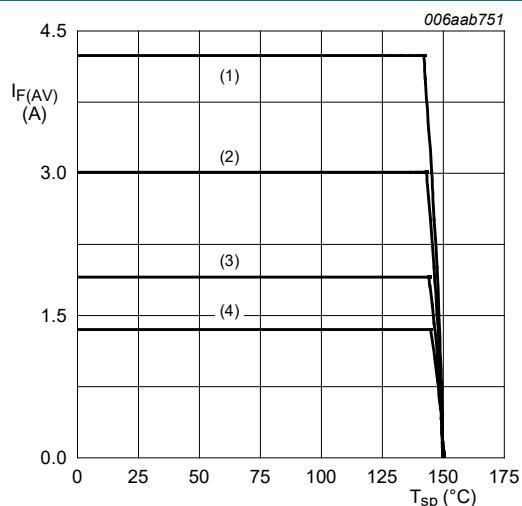
**Fig. 10. Average forward current as a function of ambient temperature; typical values**



Ceramic PCB,  $Al_2O_3$ , standard footprint  
 $T_j = 150$   $^{\circ}$ C

- (1)  $\delta = 1$ ; DC
- (2)  $\delta = 0.5$ ; f = 20 kHz
- (3)  $\delta = 0.2$ ; f = 20 kHz
- (4)  $\delta = 0.1$ ; f = 20 kHz

**Fig. 11. Average forward current as a function of ambient temperature; typical values**



$T_j = 150$   $^{\circ}$ C  
(1)  $\delta = 1$ ; DC  
(2)  $\delta = 0.5$ ; f = 20 kHz  
(3)  $\delta = 0.2$ ; f = 20 kHz  
(4)  $\delta = 0.1$ ; f = 20 kHz

**Fig. 12. Average forward current as a function of solder point temperature; typical values**

## 11. Test information

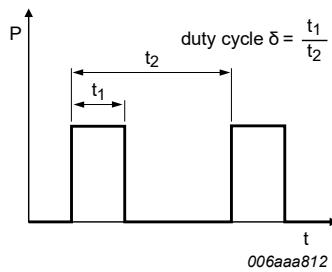


Fig. 13. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC}$$

$$I_{RMS} = I_M \times \sqrt{\delta} \text{ with } I_{RMS} \text{ defined as RMS current}$$

## 12. Package outline

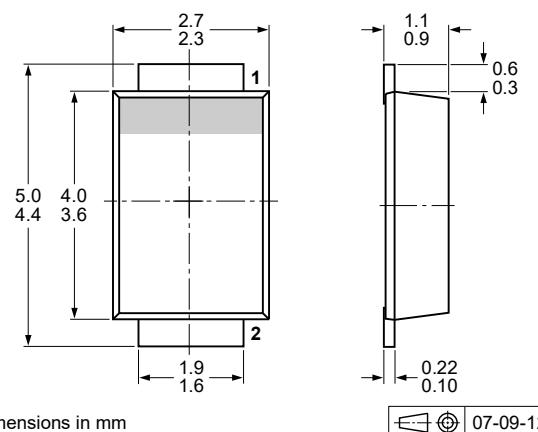


Fig. 14. Package outline CFP5 (SOD128)

## 13. Soldering

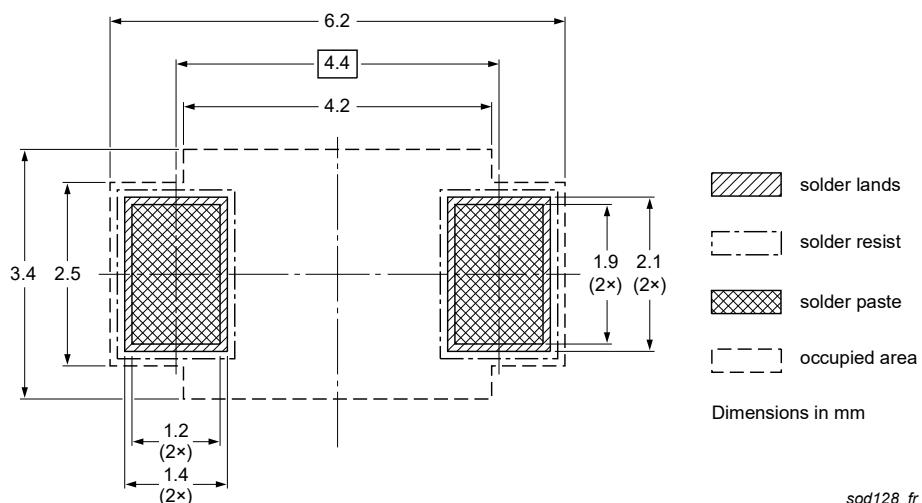
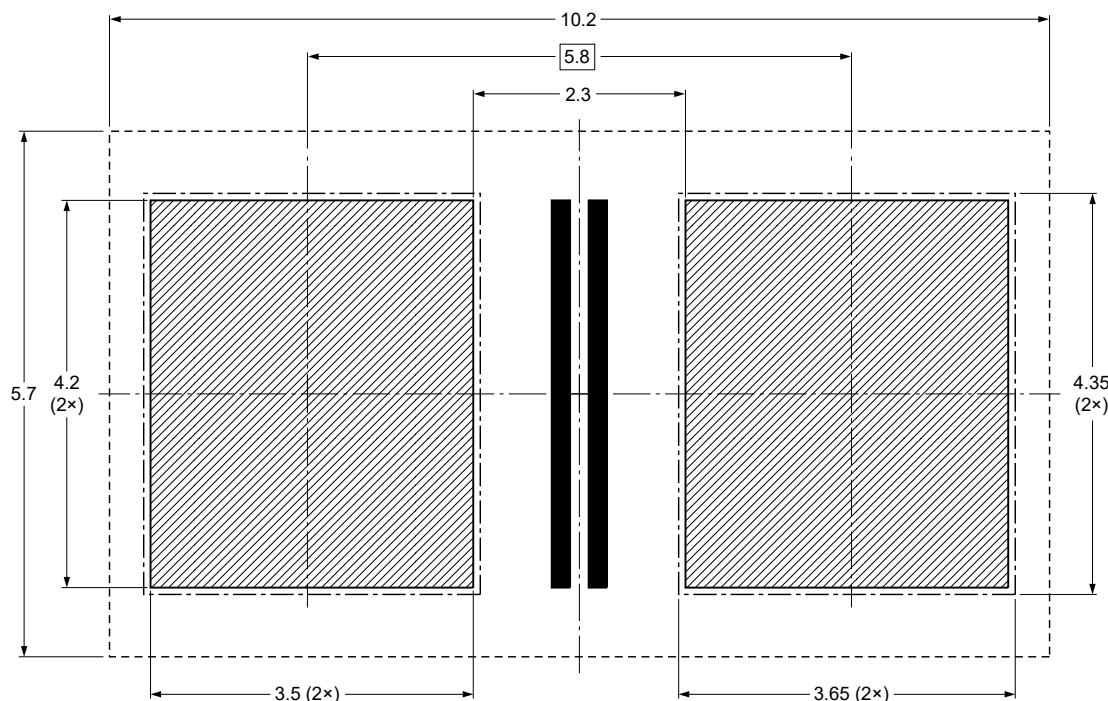


Fig. 15. Reflow soldering footprint for CFP5 (SOD128)

## Wave soldering footprint information

SOD128



occupied area

solder resist

solder lands

dummy track (solder resist and Cu free)

Dimensions in mm

Issue date 17-06-06  
17-06-07

sod128\_fw

Fig. 16. Wave soldering footprint for CFP5 (SOD128)

## 14. Revision history

**Table 8. Revision history**

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG3030EP v.3	20230401	Product data sheet	-	PMEG3030EP v.2
Modifications:	<ul style="list-style-type: none"><li>Product(s) changed to non-automotive qualification. Please refer to <a href="http://nexperia.com">nexperia.com</a> for automotive (-Q) product alternative(s).</li></ul>			
PMEG3030EP v.2	20180120	Product data sheet	-	PMEG3030EP v.1
PMEG3030EP v.1	20091209	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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